

REGULATORY COMPLIANCE

 <p>Lead Free COMPLIANT</p>	 <p>EU RoHS 2011/65 + 2015/863 COMPLIANT</p>	 <p>China RoHS COMPLIANT</p>	 <p>REACH SVHC COMPLIANT</p>	 <p>DRC CONFLICT FREE</p>
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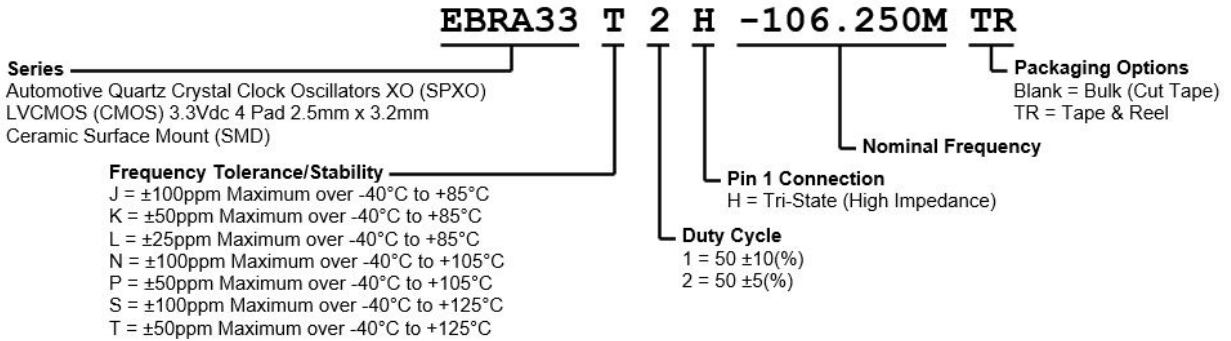
ITEM DESCRIPTION

Automotive Grade Quartz Crystal Clock Oscillators XO (SPXO) LVCMOS (CMOS) 3.3Vdc 4 Pad 2.5mm x 3.2mm Ceramic Surface Mount (SMD)

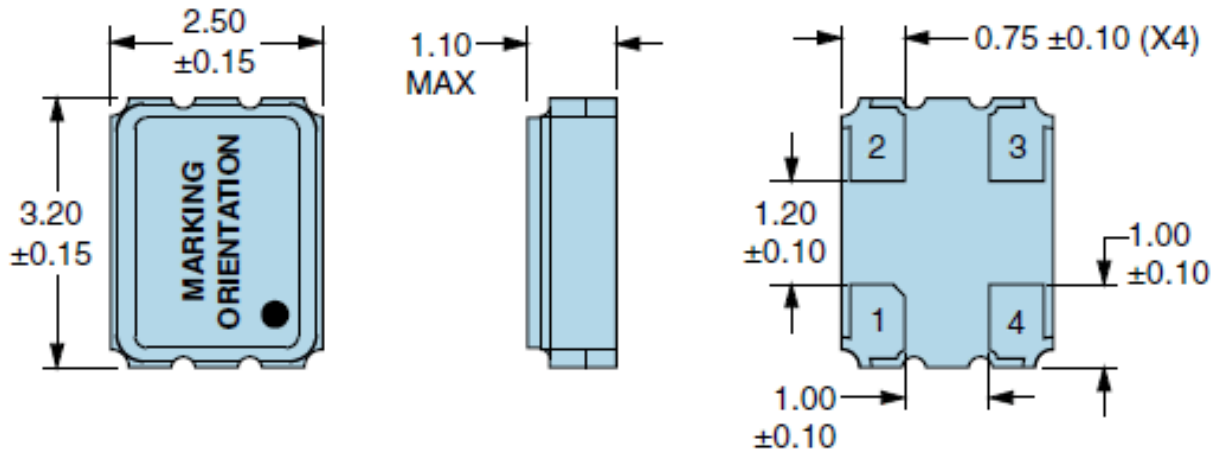
ELECTRICAL SPECIFICATIONS

Nominal Frequency	1MHz to 156.25MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance (at 25°C), Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, and First Year Aging at 25°C ±100ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±25ppm Maximum over -40°C to +85°C ±100ppm Maximum over -40°C to +105°C ±50ppm Maximum over -40°C to +105°C ±100ppm Maximum over -40°C to +125°C ±50ppm Maximum over -40°C to +125°C
Aging at 25°C	±3ppm/year Maximum
Supply Voltage	3.3Vdc ±10%
Input Current	Unloaded 10mA Maximum
Output Voltage Logic High (Voh)	IOH = -4mA 90% of Vdd Minimum
Output Voltage Logic Low (Vol)	IOL = +4mA 10% of Vdd Maximum
Rise/Fall Time	Measured at 20% to 80% of Waveform 6nSec Maximum
Duty Cycle	Measured at 50% of Waveform 50 ±10(%) 50 ±5(%)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (High Impedance)
Output Control Input Voltage Logic High (Vih)	70% of Vdd Minimum or No Connect to Enable Output
Output Control Input Voltage Logic Low (Vil)	30% of Vdd Maximum to Disable Output (High Impedance)
Standby Current	Without Load 10µA Maximum
Period Jitter (RMS)	5pSec Maximum
Period Jitter (pk-pk)	30pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

PART NUMBERING GUIDE



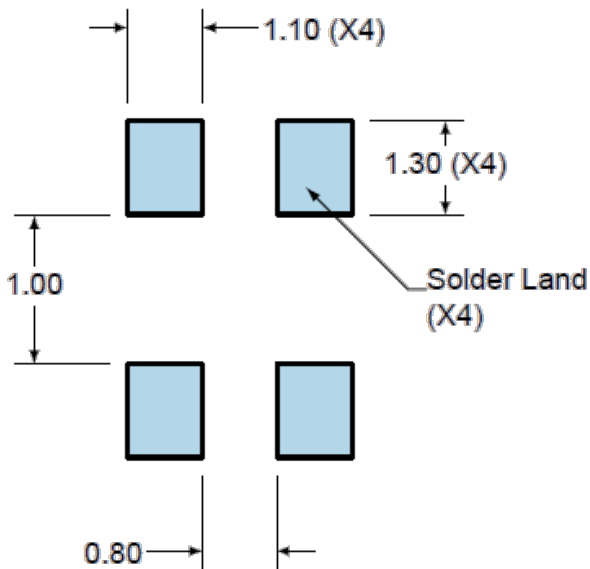
MECHANICAL DIMENSIONS



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

SUGGESTED SOLDER PAD LAYOUT

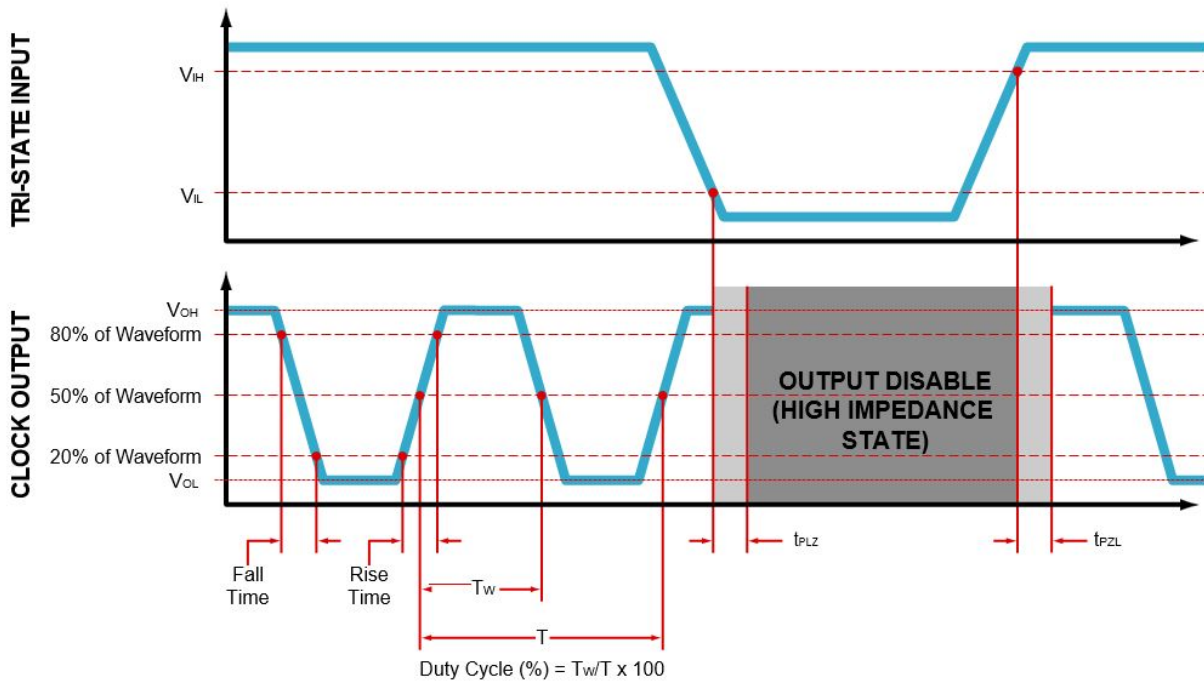


PIN	CONNECTION
1	Tri-State
2	Case/Ground
3	Output
4	Supply Voltage

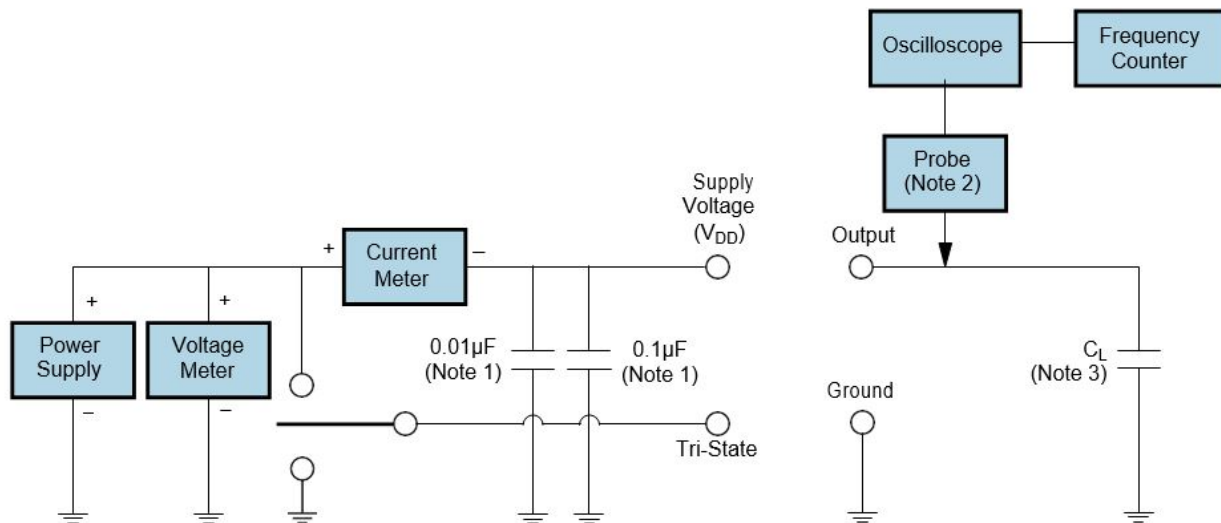
All Tolerances are ±0.1

All Dimensions in Millimeters

OUTPUT WAVEFORM & TIMING DIAGRAM



TEST CIRCUIT FOR CMOS OUTPUT



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance (<12pF), 10X Attenuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) Passive probe is recommended.

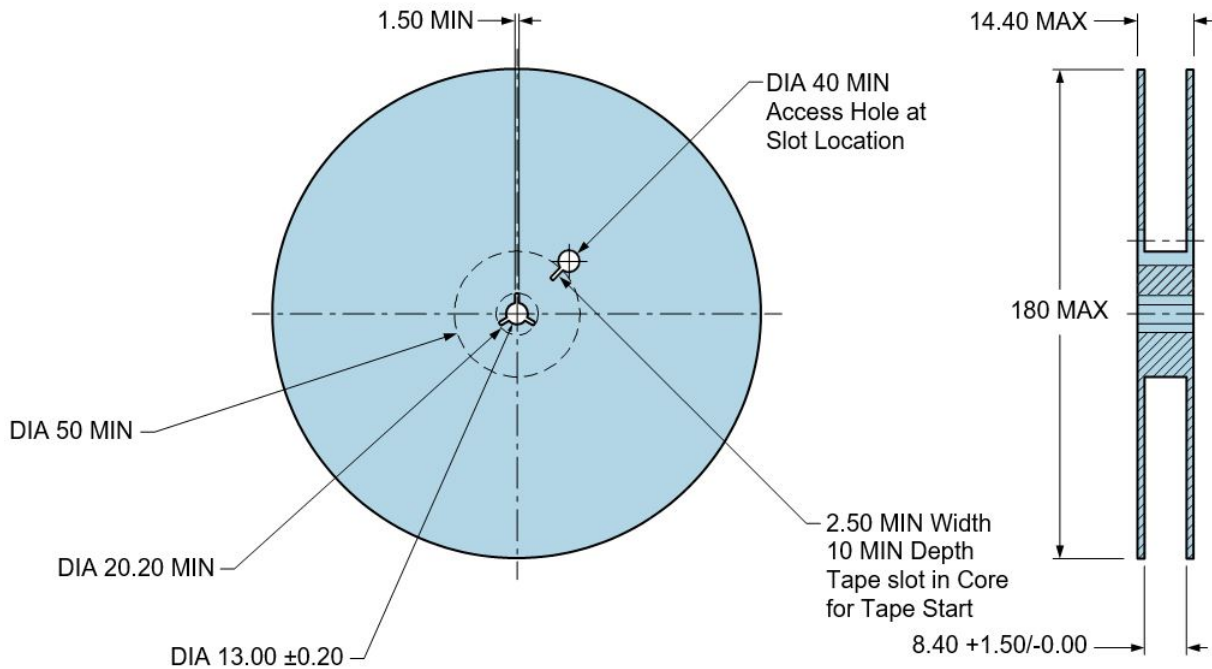
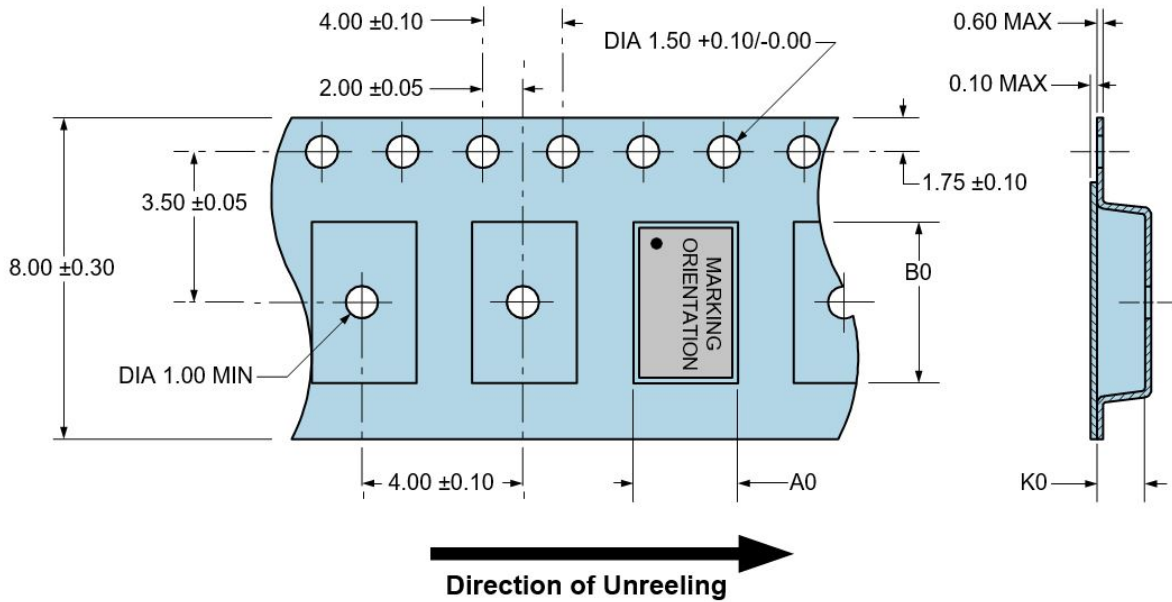
Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

TAPE & REEL DIMENSIONS

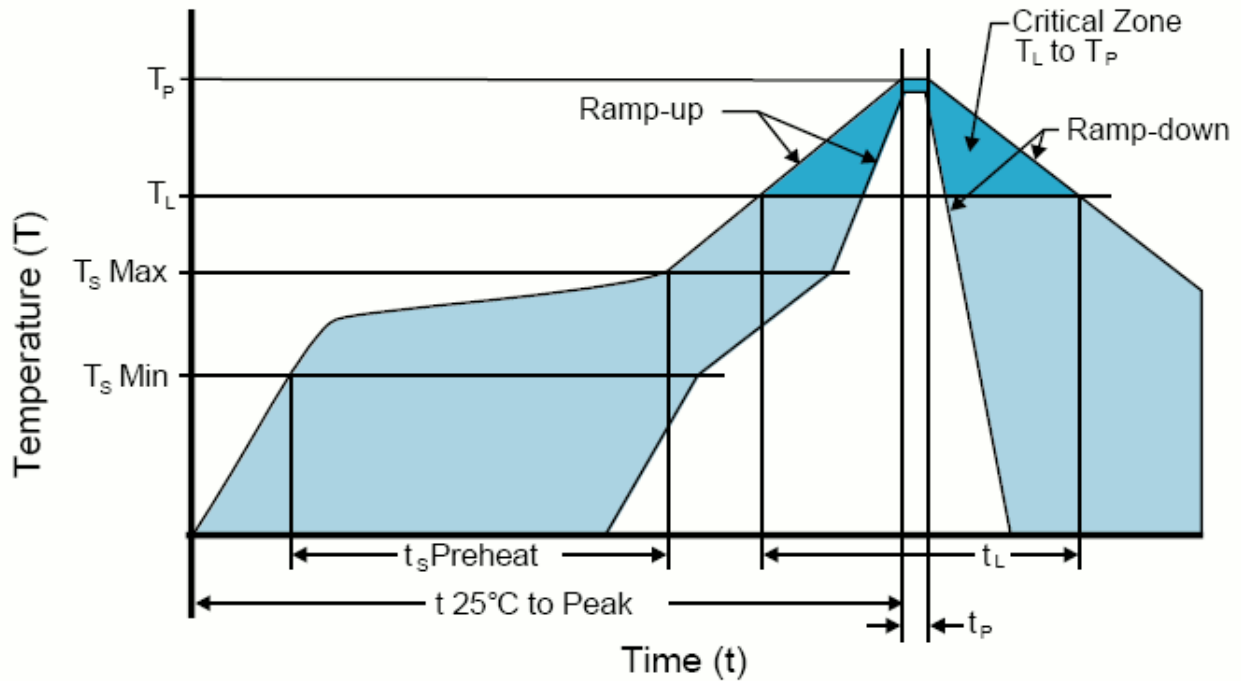
Quantity per Reel: 3,000 Units

All Dimensions in Millimeters

Compliant to EIA-481



RECOMMENDED SOLDER REFLOW METHOD



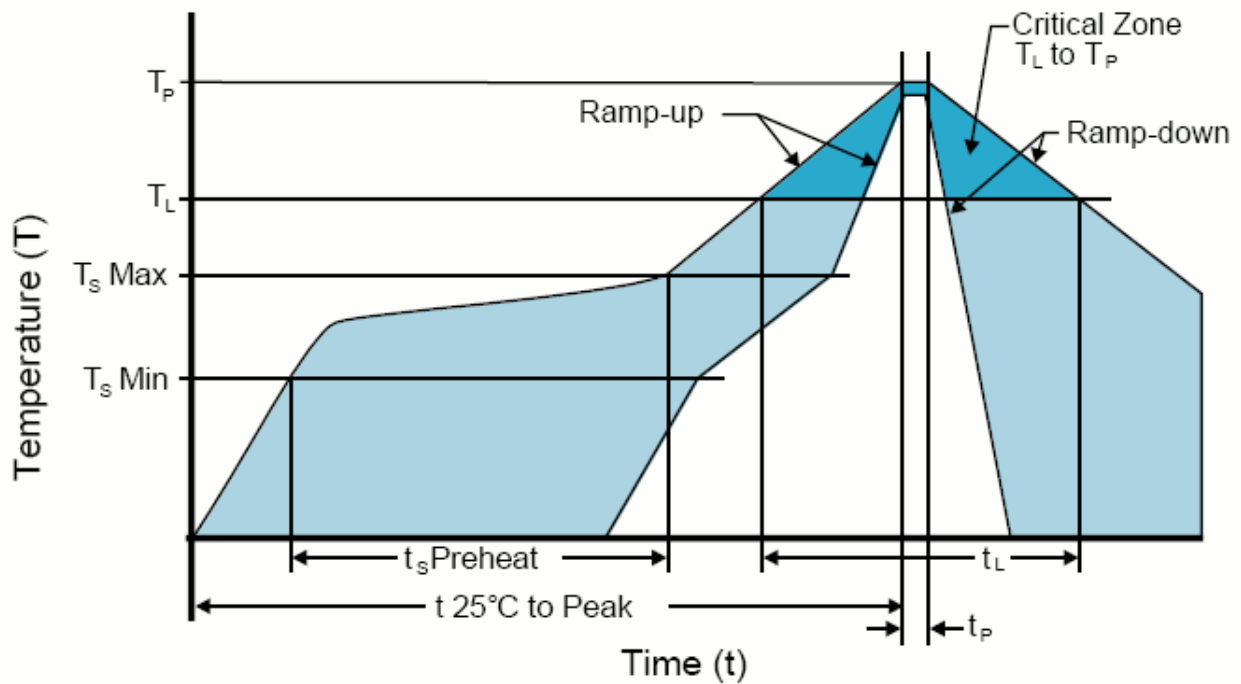
HIGH TEMPERATURE INFRARED/CONVECTION

T _S MAX to T _L (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (T _S MIN)	150°C
- Temperature Typical (T _S TYP)	175°C
- Temperature Maximum(T _S MAX)	200°C
- Time (t _s MIN)	60 - 180 Seconds
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (T _L)	217°C
- Time (t _L)	60 - 150 Seconds
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature(T _P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t _p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION

T _S MAX to T _L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T _S MIN)	N/A
- Temperature Typical (T _S TYP)	150°C
- Temperature Maximum(T _S MAX)	N/A
- Time (t _S MIN)	60 - 120 Seconds
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T _P)	240°C Maximum
Target Peak Temperature(T _P Target)	240°C Maximum 2 Times/230°C Maximum 1Time
Time within 5°C of actual peak (t _P)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperatures shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

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[SiT8209AI-32-33E-125.000000](#) [SIT8918AA-11-33S-50.000000G](#) [SM4420TEV-40.0M-T1K](#) [F335-24](#) [F335-40](#) [F535L-10](#) [F535L-12](#) [F535L-16](#) [F535L-24](#) [F535L-27](#) [F535L-48](#) [PE7744DW-100.0M](#) [CSX-750FCC14745600T](#) [ASF1-3.686MHZ-N-K-S](#) [XO57CTECNA3M6864](#) [ECS-2100A-147.4](#) [601251](#) [EP16E7E2H26.000MTR](#) [SIT8918AA-11-33S-16.000000G](#) [XO3003](#) [9120AC-2D2-33E212.500000](#) [9102AI-243N25E100.00000](#) [8208AC-82-18E-25.00000](#) [8008AI-72-XXE-24.545454E](#) [8004AC-13-33E-133.33000X](#) [AS-4.9152-16-SMD-TR](#) [ASFL1-48.000MHZ-LC-T](#) [SIT8920AM-31-33E-25.0000](#) [DSC1028DI2-019.2000](#) [9121AC-2C3-25E100.00000](#) [9102AI-233N33E100.00000X](#) [9102AI-233N25E200.00000](#) [9102AI-232H25S125.00000](#) [9102AI-133N25E200.00000](#) [9102AC-283N25E200.00000](#) [9001AC-33-33E1-30.000](#) [XLH536125.000JS4I](#) [3921AI-2CF-33NZ125.000000](#) [5730-1SF](#) [PXA000010](#) [SIT1602BC-83-33E-10.000000Y](#) [8003AI-12-33S-40.00000Y](#)